

If Taiwan Falls, the Fabs Burn: Why TSMC's Destruction Is the Inevitable Outcome of a China Invasion

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The question of whether Taiwan Semiconductor Manufacturing Company (TSMC) would be destroyed in a Chinese invasion of Taiwan is often framed as speculative, controversial, or hypothetical. In reality, the accumulated logic of modern warfare, industrial dependency, and deterrence strategy makes one conclusion increasingly unavoidable: in a kinetic invasion scenario, Taiwan's leading-edge semiconductor fabs will not survive as functioning assets. Whether through deliberate demolition, remote disablement cascading into physical ruin, or inevitable collapse under combat conditions, the facilities that anchor the global advanced-chip supply chain are effectively pre-destined to be lost. This paper argues that the "scorched earth" outcome is not an optional policy proposal but an emergent certainty produced by structural forces. The fragility of extreme-precision fabrication, the impossibility of orderly occupation, the strategic incentives of all major actors, and the tempo of modern conflict together eliminate any credible path in which advanced fabs are captured intact and brought under hostile control. Public debate has lingered on whether destruction would be moral, wise, or necessary. That debate is increasingly beside the point. Rather than asking *whether* TSMC would be destroyed, this paper reframes the analysis around *how, by whom, how quickly, and with what global consequences*. The goal is not advocacy, but clarity: to describe the industrial, military, and geopolitical realities that make the destruction of Taiwan's advanced semiconductor infrastructure the most probable outcome of invasion—and to confront the implications of that reality honestly.

Keywords: TSMC destruction, Taiwan invasion, semiconductor warfare, scorched earth strategy, fab denial, chip supply chain collapse, China Taiwan conflict, industrial warfare, advanced lithography, deterrence failure, silicon shield, modern war infrastructure.

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1. Reframing the Question: From “Would They?” to “How Could They Not?”

The dominant public discourse around Taiwan’s semiconductor facilities—particularly TSMC’s ultra-advanced fabrication plants—has often taken the form of an open question: *Would these fabs be destroyed if China invades?* This framing implies ambiguity, policy optionality, or strategic unpredictability. But upon closer examination, the question itself is misleading. The correct inquiry is not *whether* these facilities will be destroyed, but *how could they not be?* In other words, under the conditions of a real military conflict—especially one involving a large-scale amphibious or missile-based assault—the destruction of Taiwan’s leading-edge fabs is not a possibility. It is a structural certainty.

This section lays the groundwork for the paper’s thesis: that the destruction of advanced semiconductor infrastructure in a Taiwan invasion scenario is inevitable, not because it is planned or desired, but because it emerges unavoidably from the physics, logistics, and incentives of modern war.

1.1 Why Survival of Advanced Fabs Is the Wrong Baseline Assumption

Public commentary often defaults to a peacetime lens when imagining what might happen to TSMC’s fabs. In this frame, the survival of the facilities is assumed unless explicitly destroyed—like a vase that remains intact on the shelf unless someone decides to break it. This assumption is not just wrong; it is dangerously misleading.

Advanced semiconductor fabs are not robust industrial fortresses—they are **hyper-fragile ecosystems** of atomic-scale precision, dependent on uninterrupted inputs of electricity, ultra-pure water, inert gases, chemical slurries, and cleanroom sterility. These facilities do not require bombs to be disabled. A sustained power outage, vibration from nearby ordinance, contamination from debris, or the departure of key engineers can be sufficient to render a fab permanently inoperable. In this light, the **continued operability** of a fab in a warzone is the **exceptional state**, not the default. The burden of proof should rest on *explaining how* a fab could be kept running under invasion conditions—not on why it would fail.

This reframing turns the question inside out. A functioning fab in wartime Taiwan would be an engineering miracle, not a strategic baseline.

1.2 Industrial Infrastructure as a First-Day Casualty of Modern War

The concept of “first-strike targets” in modern warfare includes more than airbases, radar installations, and communication nodes. It now encompasses strategic industrial assets—

especially those that enable military capabilities, supply chains, or diplomatic leverage. Taiwan's semiconductor fabrication capacity, particularly at TSMC's leading-edge nodes, meets all three criteria. These fabs are not merely economic assets; they are strategic amplifiers of national and global power.

In any serious cross-strait conflict, it is almost certain that Taiwan's infrastructure would be targeted either directly by Chinese precision strikes or indirectly through the chaos of early invasion phases. Whether through cyberattacks on power grids, kinetic missile strikes on logistics corridors, or military control of civilian zones, the **operational continuity of the semiconductor ecosystem would collapse almost immediately.**

Moreover, China's own incentives favor early targeting or neutralization of TSMC. If a conflict is unavoidable, the value of the fabs lies not in preserving them for post-war economic benefit, but in denying them as leverage points for Taiwan and its allies. In modern warfare, **control without operability is meaningless**—and every major actor understands this.

1.3 The Difference Between Peacetime Capture and Wartime Denial

One of the most persistent fallacies in the TSMC debate is the assumption that semiconductor fabs can be "captured" in the way one might capture an oil refinery or a port. This assumption arises from peacetime analogies: a business acquisition, a regime change, a change of management. But war does not resemble an orderly handover. It resembles entropy, speed, and irrecoverable disruption.

A semiconductor fab is not just a building full of equipment—it is a **dynamically tuned, constantly calibrated** process system where uptime and precision are tightly coupled. The moment war begins, the multi-dependency matrix that supports TSMC—electrical stability, cleanroom integrity, ASML maintenance, software patches, chemical inputs, staff rotations, equipment recalibration—**collapses across multiple dimensions simultaneously.** There is no "pause and restart" button for a fab at 3nm or below.

Wartime denial, therefore, is not an act of sabotage—it is a consequence of disruption. Even if no party intends for the fabs to be destroyed, the system cannot survive the conditions imposed by war. This is why policy debates around "blowing up TSMC" often miss the point. The fabs are destroyed **by the war itself**, not by deliberate demolition.

2. Why Advanced Semiconductor Fabs Cannot Be Occupied

The common intuition that an invading force could "take over" a semiconductor fabrication facility like TSMC and resume operations under new control is deeply flawed. Semiconductor fabs are not static assets like oil fields or power plants; they are *living systems*, dependent on continuous, coordinated precision across materials, machines, software, and human expertise. Occupation does not preserve such a system—it unravels it.

This section explains why, in practical and technical terms, advanced fabs *cannot* be seized and operated by an occupying force. Their design and fragility make them inherently resistant to transfer of control under conditions of duress.

2.1 Precision Manufacturing as an Anti-Occupation Technology

At the heart of modern semiconductor fabrication is extreme precision—measured not in millimeters or microns, but in nanometers and angstroms. Every process stage—deposition, lithography, etching, doping, metrology—is governed by tolerances tighter than military weapon systems. These tolerances are not just technical challenges; they are *barriers to transfer*.

The higher the node performance (e.g., 5nm, 3nm, 2nm), the more tightly coupled the entire process becomes. Even a minor shift in vibration, humidity, temperature, or tool alignment can push yields from 95% to 5%. The cleanroom is not merely a sterile space; it is a controlled quantum environment, where even routine maintenance requires factory-wide recalibration.

This means that occupation by an external force—no matter how skilled in general engineering—is almost guaranteed to **disrupt calibration beyond recovery**. The fab's output would crash before any hostile operator could begin to understand the tuning parameters. Ironically, the more advanced and valuable the fab, the *less* survivable it is in the hands of an invader. TSMC's most sophisticated plants are, in effect, self-denial machines.

2.2 Dependence on Uninterrupted Power, Water, Chemicals, and Calibration

Advanced fabs are uniquely dependent on a stream of **critical inputs** that are easily interrupted in any conflict scenario:

- **Electricity:** A stable, uninterrupted power supply—often from dedicated substations—is essential. Even a 2-second outage can ruin entire production runs. Restarting a fab is not like flipping a switch; it requires staged calibration, requalification, and software validation.

- **Water:** Semiconductor fabrication uses vast quantities of **ultra-pure water (UPW)**—far purer than drinking water, filtered down to sub-ppb levels of contaminants. If water purification is halted or contaminated during occupation, operations stop immediately.
- **Chemicals:** Dozens of highly specialized chemicals (e.g., photoresists, etchants, slurries, dopants) are used at every stage. These must be replenished on tight schedules and often come from international suppliers. War conditions sever these links.
- **Process Calibration:** Every tool in the fab operates within a web of inter-tool calibration. Drift in one process—such as electron beam alignment in lithography—requires downstream compensations that are only known to the in-house engineering teams. A fab cannot be paused, captured, and resumed without this deep context. It is *not* a reproducible cookbook; it is a continuous, adaptive ballet.

No occupying force, even with technical training, could replace the full stack of operational integrity that these systems require. The infrastructure would begin to degrade within hours, and by the time a new operator could hypothetically take control, the damage would already be terminal.

2.3 Human Capital Fragility: The Non-Transferability of Tacit Expertise

Perhaps the most overlooked aspect of fab non-occupiability is the **human factor**. The assumption that China—or any other invading force—could simply replace or compel the cooperation of TSMC's engineers overlooks the depth and specificity of the talent involved.

Leading-edge fabs operate with thousands of **deeply embedded specialists**, many of whom have spent years fine-tuning proprietary processes, tool calibrations, and emergency response protocols. Their knowledge is *tacit*, not fully documented—passed through training, mentorship, and lived experience. Much of what keeps a fab running is not found in manuals or schematics; it lives in the heads of process engineers, tool operators, and maintenance crews who operate within an organizational rhythm.

This human knowledge is non-transferable under stress. Engineers cannot be forced at gunpoint to perform system-level coordination across litho, etch, and deposition modules. Even willing personnel could not maintain output without access to partner tools (like ASML's EUV systems) or ongoing global supplier support.

Moreover, many of TSMC's employees would likely evacuate, defect, or go underground in the event of war. Whether due to fear, ethical objection, or sheer logistical impossibility, the human layer of fab functionality would vanish—rendering the physical assets inert.

In short, without the minds that sustain them, the machines mean nothing. A fab under occupation is a corpse without its nervous system.

3. The Invasion Timeline Problem

Even if we ignore the technical fragility of semiconductor fabs and their deep entanglement with global supply chains, there remains a blunt, physical reality that overrides any abstract optimism: **timing**. The operational tempo of modern military conflict, especially in the Taiwan Strait, is measured in minutes and hours—not days or weeks. Every credible invasion scenario—whether gray-zone hybrid warfare or full-scale kinetic assault—moves at a speed and intensity that renders the idea of “safe handover” of critical infrastructure completely unrealistic.

This section explains why **the speed required for an invasion to succeed guarantees the destruction of the very facilities an invader might hope to preserve**. In short: *if it's fast enough to work, it's violent enough to break everything*.

3.1 Why Any Invasion Fast Enough to Succeed Is Violent Enough to Destroy

Successful invasions in modern warfare, especially against technologically advanced and strategically defended regions like Taiwan, must unfold with overwhelming speed. China cannot afford a slow, attritional conflict over Taiwan, as it would invite intervention, international condemnation, economic collapse, and possible military entanglement with the United States and regional allies. The operational doctrine, therefore, must be one of **rapid saturation and decapitation**—paralyzing Taiwan’s command structure, disabling its defenses, and physically controlling key assets in a matter of hours to days.

But this very speed requires kinetic force at scale: **missile barrages, airborne assaults, cyberattacks, and special operations teams** inserted under fire. These tools of shock warfare are not compatible with infrastructure preservation. The missiles that suppress radar also shred substations. The jamming that blinds air defense also disables civilian communications. Airborne landings that target airfields and government centers create chaos in surrounding industrial zones.

No military campaign intense enough to take Taipei in under 72 hours—a threshold often modeled by war game analysts—can avoid inflicting **disabling collateral damage** on Hsinchu or Tainan, where TSMC’s most advanced fabs are located. Any slower timeline guarantees foreign intervention; any faster timeline guarantees physical ruin. There is no third path.

3.2 Air Campaigns, Missile Strikes, and Collateral Inevitability

Semiconductor fabs are not buried bunkers. They are expansive, delicate facilities with strict environmental tolerances, located in industrial parks surrounded by civilian and logistical infrastructure. While TSMC's flagship Fab 18 or Fab 15 might not be a direct target in an initial strike, the infrastructure that supports them—**electrical substations, transportation links, water treatment plants, fuel depots, and digital control centers**—certainly will be.

Even precision-guided munitions create **shockwaves, vibration, dust infiltration, and infrastructure failure** within a several-kilometer radius. There is no version of a mass air campaign where the surrounding environment of a fab is not contaminated, shaken, or degraded. Semiconductor plants cannot function in the proximity of that level of disturbance.

Moreover, even **defensive fire**—such as Taiwan's interception of incoming missiles—generates risk to fab infrastructure. Interceptor impacts, debris from drones, and panic-triggered shutdowns of regional power grids can all render production lines useless within minutes. When thousands of rounds, decoys, drones, and missiles are moving simultaneously across a narrow island, **collateral inevitability becomes the operating assumption**, not a risk.

3.3 Why “Secure First, Operate Later” Is Operationally Incoherent

Some analysts cling to the idea that an invading force might be able to “secure” Taiwan's critical infrastructure—particularly TSMC's fabs—and bring in its own engineers or co-opt local staff later. This assumption reveals a fundamental misunderstanding of both military operations and semiconductor processes.

First, the “secure, then operate” model is a **logistical and tactical fantasy**. The security phase of a Taiwan invasion would require neutralizing **thousands of defensive positions**, subduing major urban centers, and establishing **air and sea dominance**—all while sustaining enormous disruption to transport, communications, and utilities. Any timeline in which a fab is “secured” while still intact is **incompatible with the rest of the invasion's operational reality**.

Second, by the time any meaningful level of control is established, the fab will have already **failed irreversibly**. TSMC fabs run on **tight process timing**, where even temporary contamination, vibration, or misalignment in just one stage can destroy weeks of wafers and require **months of re-qualification**. Power surges, brief water loss, or data synchronization failures during occupation would already have rendered the equipment inoperable.

Finally, fab operability is not a binary. It is not “off until secure, then back on.” It is a **continuous ballet of interdependent systems** that cannot simply be resumed like flipping a switch. Even if a

facility is physically intact, by the time an occupying force reaches it, the ballet has long since collapsed.

In this context, “secure first, operate later” is not a strategy. It is a mirage.

4. Strategic Incentives Guarantee Denial

Even if semiconductor fabs could somehow be physically preserved in an invasion—and even if occupation were somehow technically feasible—there would still remain the issue of **strategic intent**. The incentives of the three major actors involved—Taiwan, its allies (especially the United States), and China—all point toward **denial, not preservation**, as the most rational outcome. Whether through deliberate demolition, remote disablement, or letting nature take its course under war conditions, none of the major players has a strong incentive to preserve TSMC’s fabs for Chinese control.

This section examines the **geostrategic logic** of each party and shows how denial becomes the convergent point of their otherwise opposing interests.

4.1 Taiwan’s Incentives: Loss Prevention Versus Loss Mitigation

Taiwan's optimal strategy is obviously to **prevent invasion entirely**. But if deterrence fails, and invasion begins, then Taiwan's strategy shifts to **loss mitigation**. In this wartime scenario, the island’s leadership must assume that their key national assets—including TSMC—will be targeted or seized. The calculus becomes brutally simple: **better destroyed than captured**.

TSMC is often described as Taiwan’s “silicon shield”—a deterrent based on interdependence with the global economy. But shields are only effective before the blow lands. Once hostilities commence, that same asset becomes a **target**, not a buffer. Taiwan’s government cannot allow the world’s most advanced chipmaking infrastructure to be transferred intact to the invader. Doing so would represent both a catastrophic **strategic loss** and a profound **psychological defeat**.

Therefore, Taiwan is almost certainly preparing, privately and quietly, for **contingency plans** that ensure fab non-transferability. This does not require pre-wired explosives or cinematic self-destruction sequences. It may be as simple as disabling power, evacuating key staff, corrupting process recipes, or ensuring contamination. The point is not flamboyant sacrifice—it is **silent denial**. Once defense fails, Taiwan’s highest incentive becomes *depriving the invader of benefit*.

4.2 Allied Incentives: Denial Outweighs Preservation

For the United States, Japan, and other regional allies, the situation is equally stark. The global semiconductor supply chain cannot tolerate China capturing Taiwan's leading-edge fabs intact. The **technological asymmetry** that currently exists—largely enabled by Taiwan and supported by Dutch, American, and Japanese firms—would collapse. The U.S. would see its **national security, AI dominance, and defense readiness** eroded overnight.

Allied powers, therefore, have a compelling incentive to **ensure that leading-edge nodes do not fall into Chinese hands**, even if that means **supporting or enabling their destruction**. This logic has already surfaced in public statements from former U.S. national security officials, who have openly endorsed the idea of disabling or destroying TSMC if China invades. While such statements are politically sensitive, they reflect a deeper policy consensus: **denial is preferable to capture**.

Allies may not need to fire a single shot to enact this denial. Instead, they can sever the **supply of critical lithography tools, process chemicals, software licenses, and calibration services**—crippling fab functionality remotely. In a worst-case scenario, kinetic intervention to prevent fab capture might even be considered. The sheer strategic value of these facilities means that **denial is a global interest**, not just a Taiwanese one.

4.3 China's Incentives: Speed Over Salvage

From China's perspective, the value of TSMC's fabs lies primarily in **denying them to others**, not in capturing them for seamless integration into domestic industry. The idea that the PLA could take over a 3nm fab and resume production under a new flag within weeks is not only technically impossible—it is *strategically irrelevant*. What matters is control, not continuity.

China's political and military planning emphasizes **decisive action, rapid escalation control, and information dominance**. In such a doctrine, speed is paramount. The longer an invasion drags on, the more likely it is to trigger U.S. intervention, sanctions, and diplomatic isolation. Beijing has little incentive to prioritize **surgical precision and infrastructure preservation** when the strategic goal is to collapse Taiwan's sovereignty and break the U.S.-led containment arc.

Moreover, the optics of restoring chip production for the global market are complicated. If China captures and restarts TSMC, it would face **massive embargoes**, legal retaliation, and intellectual property blockades from the rest of the world. The market for those chips would evaporate. The only scenario in which fab salvage would be economically viable is one in which China has **already won the larger war**—in which case, chip capacity is secondary to geopolitical transformation.

In short, China's primary incentive is **political control**, not technical inheritance. The destruction of TSMC—whether as collateral damage or deliberate denial—does not frustrate China's strategy. It likely **serves** it.

5. Destruction Without Explosives: How Fabs Die Even If No One “Blows Them Up”

Much of the public imagination around the destruction of semiconductor infrastructure involves cinematic images—fabs wired with explosives, dramatic detonations, and acts of sabotage. But the truth is far more mundane and, in a way, more terrifying: **fabs can die quietly**. Even without a single bomb falling, without direct attack or intentional sabotage, Taiwan’s leading-edge fabs can become permanently inoperable due to systemic disruption.

This section explains the mechanisms by which semiconductor fabrication capacity at the 5nm, 3nm, or 2nm nodes can collapse entirely **without any need for explosive devices or direct combat inside the facilities themselves**.

5.1 Loss of EUV Functionality and Irreversible Process Drift

Extreme Ultraviolet Lithography (EUV) is the cornerstone of sub-7nm semiconductor production. It is not merely another tool in the fab—it is the central enabler of the entire process. EUV machines are complex systems requiring **atomic-level precision, continuous recalibration, and constant manufacturer support**. TSMC’s EUV systems are made exclusively by ASML in the Netherlands and supported by tightly controlled supply chains from the U.S., Japan, and Europe.

If TSMC's fabs lose access to real-time servicing, software updates, proprietary calibrations, or replacement components from ASML, **EUV functionality degrades within days or weeks**. Tiny misalignments in beam optics, phase uniformity, or wafer staging rapidly lead to **process drift**—a state in which patterning becomes unreliable, yields collapse, and no amount of internal tweaking can recover operability without external support.

What makes this drift irreversible under wartime conditions is that **each EUV machine is individually tuned and uniquely interlocked with the fab’s process recipes**. Once that tuning is lost—through temperature variation, vibration, loss of power, or failed synchronization—the fab cannot simply be “retuned” locally. The recovery process requires specialized personnel, access to diagnostic servers, and trust-based coordination with ASML, all of which become impossible under invasion conditions.

In short, if the EUV fails—or is even just paused for too long—the fab dies.

5.2 Software, Calibration, and Tooling Dependency Collapse

Modern fabs are not manually operated facilities. They are **cyber-physical systems**, where software orchestrates hundreds of process tools, robotic material handlers, recipe adjustments, and in-line metrology. This software is not generic. It is **highly proprietary**, closely guarded, and dependent on encrypted licenses, remote updates, and cloud-tethered support portals.

TSMC's production orchestration software is co-developed with partners and locked down against theft or misuse. If an invader seizes the fab, this software **automatically deactivates or degrades**, not by sabotage but by loss of authentication and violation of network trust boundaries. The systems that control plasma uniformity in etchers, bake profiles in furnaces, or laser timing in litho tools require continuous synchronization across the fab. Any **disconnect—whether due to cyberattack, equipment downtime, or deliberate access cutoff—leads to systemic collapse**.

Additionally, process tools depend on **multi-vendor interoperability**: Japanese firms (like Tokyo Electron) provide deposition tools, American firms (like Applied Materials and Lam Research) provide etchers and inspection systems, and each has unique firmware and usage constraints. Under normal conditions, this ecosystem is invisible. Under occupation, it **fractures instantly**. Tools cannot be serviced, recalibrated, or updated. Errors accumulate, precision fails, and throughput collapses.

This isn't theoretical. Fab operations depend on **hundreds of software-hardware feedback loops** that degrade rapidly in the absence of institutional support. Once the tooling ecosystem collapses, there is no way back.

5.3 Why Months of Downtime Equals Permanent Loss at the Leading Edge

The modern semiconductor race is not just about technology—it is about **tempo**. At the leading edge, even a few months of downtime represents **irrecoverable loss**. The reason is twofold: first, because technological leadership compounds over time; and second, because **the longer a fab is down, the harder it is to restart**.

At 3nm and below, fabs run wafer production cycles that span multiple months. If a fab is down for 4–6 weeks, it loses not just output but **pipeline integrity**: partially processed wafers become useless, queued lots lose synchronization, and calibration settings across interdependent tools drift apart. Bringing a fab back online is not a matter of restarting machines. It is a **full system-level revalidation process** that can take **several quarters**, even in peacetime, with full vendor support.

Now consider that fab restarts under occupation would be attempted **without vendor cooperation, under embargo, amid geopolitical hostility**. This is not just a logistical problem—it is a strategic impossibility. By the time China could hypothetically bring a fab back online, the rest of the world will have moved on to **2nm, gate-all-around transistors, or even post-CMOS paradigms**.

In the semiconductor world, **downtime equals death**. Any pause long enough to be induced by war is long enough to become terminal.

6. Physical Destruction Scenarios

Up to this point, we have shown that Taiwan’s advanced semiconductor fabs can be rendered permanently inoperable without any physical targeting at all—through systemic disruption, supply-chain cutoff, and process collapse. But it is equally important to understand that **physical destruction remains both plausible and, in many scenarios, probable**. Whether as a preemptive act of denial, an unintended consequence of high-intensity conflict, or a calculated strike during battle, **the physical ruin of TSMC’s crown jewel facilities is not only imaginable—it is operationally baked into most invasion timelines**.

This section explores the main categories of physical destruction and why, in the context of extreme fab fragility, even partial kinetic damage can have effects functionally identical to total obliteration.

6.1 Preemptive Demolition Versus Battlefield Destruction

There are two broad categories of fab destruction: **intentional preemptive demolition** and **unintentional destruction amid battle**. The former is a policy-driven act, the latter a tactical inevitability.

- *Preemptive demolition* refers to actions taken by Taiwan itself—or conceivably by its allies—in the final hours before a facility is lost to invading forces. This could involve explosive charges placed in critical substations, hard-drive wiping and sabotage of process servers, deliberate contamination of cleanrooms with chemical agents, or the destruction of high-value components such as EUV optics. The goal is denial, not devastation—ensuring that the fab, even if seized, cannot function again.
- *Battlefield destruction*, by contrast, is what happens when kinetic warfare engulfs the area around TSMC’s major sites—particularly in Hsinchu, Tainan, and Taichung. The People’s Liberation Army’s (PLA) likely approach to seizing Taiwan includes missile

saturation, airborne insertion, and electronic warfare, all of which generate cascading physical effects: shockwaves, fires, power surges, structural damage, and debris. In this scenario, the fabs are not "targeted" per se—they are **overrun and crushed by the tempo of combat**.

Notably, **Taiwan may choose the former precisely because it sees the latter as inevitable**. If battle is coming to the gates of Fab 18, then taking action to neutralize it before occupation is not sabotage—it is strategic foresight.

6.2 Air and Missile Strike Effects on Ultra-Clean Environments

Semiconductor fabs are not hardened bunkers. They are **fragile, low-tolerance environments** where the ambient particle count is regulated to be lower than outer space. The moment that seal is broken—by blast overpressure, shockwave vibration, or even just prolonged proximity to industrial fires—the fab is no longer viable.

A modern air campaign, especially one designed for saturation and disorientation, involves **missiles, drone swarms, decoys, electronic jamming, and countermeasures**. While Taiwan's fabs may not be direct targets, the critical infrastructure surrounding them—electrical substations, transformers, water lines, chemical depots, and roads—*will* be. Explosions within even a few hundred meters of a fab can cause:

- **Vibration-induced de-alignment** of lithography tools
- **Power spikes** that destroy precision equipment
- **Smoke infiltration** into clean zones through HVAC reversal
- **Collateral fires** from neighboring buildings or vehicles
- **Debris shockwaves** that compromise structural integrity

Once a fab's ultra-clean status is lost, **every wafer in production must be discarded**, and the entire facility undergoes a decontamination and requalification cycle that can take *months to years*—assuming the tools survived at all.

Thus, even in "lucky" scenarios where no bomb hits the fab directly, **the environment itself becomes incompatible with precision manufacturing**. Military force does not need to destroy the tool to destroy the process.

6.3 Why Partial Damage Is Equivalent to Total Loss

There is a common misconception that fabs can be damaged and then repaired over time, like a power plant or bridge. This notion fails to grasp the **systems-level interdependence** of modern chip manufacturing. At TSMC's leading-edge fabs, every component of the environment—physical, digital, chemical, and human—is tuned to exacting specifications. If even a single link in the chain is broken, the entire operation **collapses as a coherent system**.

Partial damage, therefore, does not reduce fab capacity by a fraction—it often reduces it to zero. Consider:

- If **cleanroom integrity is breached**, the fab must halt and undergo full revalidation.
- If **EUV optics are scratched or cracked**, repair is impossible without returning the component to ASML.
- If **process control software is corrupted** or rendered nonfunctional by data loss, the recipes that coordinate thousands of operations are unusable.
- If **specialist staff evacuate** or refuse to work under duress, the tacit operational knowledge vanishes.

Even if a facility's walls remain standing and its tools appear undamaged, **a handful of missing or corrupted elements can turn the entire site into dead infrastructure**.

In this context, partial damage is not a lesser evil—it is a **functional death sentence**. The idea that China could “fix up” or gradually restore a moderately damaged fab is not grounded in semiconductor reality. Once degraded, a leading-edge fab cannot be rebooted. It must be **rebuilt**—a multi-year, multinational, multi-billion-dollar undertaking.

7. The Myth of the “Captured, Working Fab”

A persistent misconception in media narratives and some policy debates is the idea that China might “capture” TSMC's facilities during an invasion, much like a victorious army might seize an oil field, power plant, or weapons factory—and resume operations under new management. The appeal of this idea lies in its simplicity: a highly valuable asset, taken intact, repurposed for the conqueror's gain.

This section dismantles that myth. It explains why **industrial precedent does not apply**, why **semiconductor fabs cannot be reverse-engineered in situ**, and why **hopes of post-war restoration of leading-edge nodes are based on deep misunderstandings of how modern fabrication systems function**.

7.1 Why Historical Industrial Captures Don't Translate

Throughout the 20th century, military campaigns often featured the seizure of industrial assets. Germany's synthetic fuel plants, France's factories under Nazi occupation, or post-war Soviet acquisition of German rocket expertise are cited as precedents. In these cases, conquerors repurposed captured infrastructure—sometimes even improving it.

But semiconductor fabs are not like steel mills, chemical refineries, or assembly plants. Those older assets were **mechanical, modular, and physically legible**: their operation could often be deduced from inspection, and their restoration could proceed with local expertise, parts, and utilities. Semiconductor fabs, by contrast, are **epistemically opaque**—their processes are not evident from hardware alone.

More importantly, **modern fabs are deeply embedded in global supply webs**, not just in terms of materials but in terms of software, support, and live tuning. There is no historical example of a wartime industrial seizure that involved **hundreds of vendors, real-time cloud authentication, and nanometer-scale process coupling**. The wartime seizure analogy simply **does not map** onto this domain.

7.2 Why Reverse-Engineering Fabs Is Not Like Reverse-Engineering Hardware

Another flawed assumption is that if China could capture a fab—even a degraded one—it could slowly reverse-engineer it, learning from the tools, the recipes, or the remaining staff. After all, China has proven adept at hardware reverse-engineering across numerous domains, from consumer electronics to military drones.

But a semiconductor fab is not a discrete object like a missile or microchip—it is a **continuous process**, orchestrated across thousands of steps, machines, and feedback loops. Capturing the machines is not sufficient. Without access to **encrypted process control software, active vendor integration, and continuous metrology-based recipe adjustment**, the fab's state is essentially indecipherable. TSMC's proprietary value lies not in the machines it buys, but in **how those machines are coordinated and tuned**.

Reverse-engineering a fab would require **more than blueprints or tool observation**; it would require recreating entire feedback architectures built over decades—tied to staff, supply chains, environmental conditions, and confidential process IP. Most of this knowledge is not on paper. It is in the people, the routines, the millions of measurements accumulated over time, and the adaptive recipes evolved through trial-and-error.

In practice, **reverse-engineering a working fab is closer to reverse-engineering a symphony performance than reverse-engineering a violin**.

7.3 The Fallacy of Post-War Restart Assumptions

A final version of the captured-fab myth takes a more optimistic form: perhaps the fab is lost in the war, but after hostilities end—regardless of who controls the island—it can be restarted. This belief underpins some economic analyses that forecast post-war recovery curves based on reconstruction timelines from past conflicts.

But this is a fallacy—because **semiconductor production does not restart where it left off**. It evolves. While the fab sits idle, the global industry moves on: node shrinks advance, new transistor architectures emerge, capital shifts toward more stable regions, and entire value chains rewire. Even a **six-month pause** can make a cutting-edge fab functionally obsolete.

More critically, **restarting a fab is not like reopening a factory**. It involves:

- Rebuilding lost trust with global partners (ASML, Cadence, Applied Materials, etc.)
- Requalifying every tool to nanometer tolerances
- Re-establishing logistical routes for ultra-pure chemicals
- Re-onboarding staff who may have fled, defected, or psychologically disengaged
- Re-securing IP and digital control rights potentially lost or revoked during conflict

And all of this would occur in a **radically different geopolitical context**—likely one of sanctions, reputational trauma, and fractured alliances.

A post-war TSMC is not a rebooted TSMC. It is, at best, a shell of its former self, lagging behind the global frontier, and **irreversibly severed from the confidence networks that once made it the world's most advanced chipmaker**.

8. Why Public Denials and Ambiguity Persist

Given the overwhelming evidence that Taiwan's semiconductor fabs cannot be captured intact and that their destruction—whether through process collapse, supply cutoff, or kinetic force—is essentially guaranteed in a war, one might ask: *Why doesn't anyone say this clearly? Why do governments, executives, and analysts continue to speak in cautious terms, deny scorched-earth planning, and avoid acknowledging the inevitable?*

The answer lies in the nature of deterrence, the strategic value of ambiguity, and the risks of prematurely escalating a fragile balance. In a world on the brink of potential great-power conflict, **saying what everyone knows can sometimes be more dangerous than silence**.

8.1 Deterrence Signaling Versus Operational Planning

In the realm of national security, there is a fundamental distinction between **deterrence signaling** and **operational planning**. Deterrence is what a state communicates publicly in order to prevent aggression; operational planning is what it prepares privately in case deterrence fails.

When leaders in Taiwan or the United States deny that TSMC would ever be destroyed, or that contingency plans exist to disable fabs, they are not necessarily lying. They are speaking within the **deterrence register**—projecting stability, interdependence, and confidence in peaceful outcomes. These messages are designed not to reveal truth, but to **shape adversary expectations** and to maintain the status quo.

Meanwhile, behind closed doors, military planners, security advisors, and fab executives **prepare for the worst**. Remote-disable switches, classified denial protocols, personnel evacuation plans, and firmware kill codes may all exist without ever being publicly acknowledged. The silence is strategic. To confirm such plans would weaken their value in deterrence terms and could spark political backlash or preemptive escalation.

8.2 The Necessity of Ambiguity Before Conflict

Ambiguity plays a vital role in deterring aggression. In situations of asymmetric risk—such as the Taiwan Strait—**clarity can invite miscalculation**. If Taiwan were to publicly state that it would destroy TSMC rather than let it be captured, China could interpret that as an admission of weakness or a provocation, accelerating its invasion timeline to preempt such action.

Likewise, if the United States or Japan were to openly support the destruction or disablement of Taiwan's chipmaking infrastructure in case of war, it could fracture alliances, panic markets, or be used by China to justify aggression under the guise of "economic terrorism." Such statements could also embolden hardliners who wish to frame Taiwan not as a victim, but as a trigger for global disruption.

Therefore, **ambiguity functions as a pressure valve**, maintaining peace through strategic uncertainty. Each side understands what is likely to happen—but no one forces the issue by confirming it. In nuclear doctrine, this is called **constructive opacity**. In semiconductor geopolitics, it is no different.

8.3 Why Confirmation Would Weaken, Not Strengthen, Stability

There is a common belief in some policy circles that clarity enhances stability. But in the case of TSMC and Taiwan's semiconductor infrastructure, **confirmation of denial plans would likely destabilize the situation**. It would:

- Undermine Taiwan's image as an indispensable global partner, suggesting it may itself sabotage global supply chains
- Embolden China to act before denial protocols are implemented, leading to **faster and bloodier escalation**
- Place TSMC employees and executives at risk by making them targets of coercion or kidnapping
- Trigger capital flight and insurance collapse in Taiwan's high-tech sector, weakening deterrence further

Moreover, explicit confirmation would **politicize TSMC as a weapon**, rather than a civilian economic entity. This would transform it from a shield into a fuse.

In practice, all parties involved—including Taiwan, China, and the U.S.—**benefit from the shared illusion that TSMC can be preserved**, even as they each prepare, quietly, for its loss. This paradox is what sustains the current peace, however fragile.

To break that illusion is to play with fire. Ambiguity persists not because the truth is unknown—but because **acknowledging it might light the match**.

9. Global Consequences of Fab Destruction

The destruction of TSMC's leading-edge semiconductor fabrication facilities would not be a regional event. It would be a **global shockwave**, rippling across nearly every industry, economic system, and geopolitical alliance. The entire digital age rests on a fragile foundation: a handful of nanometer-scale production nodes centered in Taiwan. Their sudden loss would **reverberate from data centers in Oregon to robotics labs in Seoul, from car factories in Germany to missile programs in Israel**.

This section maps the consequences across three time horizons—**immediate, medium-term, and long-term**—to highlight just how deeply the world's infrastructure, security, and political economy are entangled with what sits on Taiwan's western plains.

9.1 Immediate Effects on AI, Automotive, Defense, and Cloud Computing

In the first hours and days following the destruction or disablement of TSMC's advanced fabs, the most visible impact would be in **supply chain paralysis** and **panic pricing** across four critical sectors:

- **Artificial Intelligence (AI):** The training and deployment of large AI models—from OpenAI's frontier systems to China's domestic LLMs—depend on **TSMC-fabricated chips**, especially those from NVIDIA, AMD, and Google's custom TPU programs. These chips are made at TSMC's 5nm and 3nm nodes. A halt in production would immediately affect **GPU availability**, triggering rationing, skyrocketing prices, and delays in model development. Major AI labs would face a hardware bottleneck that no software optimization could overcome.
- **Automotive:** Modern cars—especially electric vehicles—contain dozens of chips for safety, sensing, power management, and autonomous systems. While not all are leading-edge nodes, many originate from **TSMC's legacy and mid-range fabs**. In a crisis, even these would be impacted. Automakers would be forced to **suspend production lines**, reconfigure designs, and compete fiercely for dwindling chip supply from secondary sources like GlobalFoundries or Samsung. The global auto market would see **price hikes, delivery delays, and supply rationing**.
- **Defense and Aerospace:** Precision-guided munitions, radar systems, encrypted communications, and advanced avionics depend on **TSMC-made semiconductors**, including radiation-hardened variants and low-power control logic. The sudden loss would create **vulnerabilities in NATO arsenals, delays in weapons production, and scrambles to requalify alternative sources**. In a wartime setting, this translates directly to **reduced operational readiness**.
- **Cloud Computing and Data Centers:** The hyperscale infrastructure of Amazon, Microsoft, Google, Alibaba, and others runs on **custom chips—many of which are designed in the U.S. and fabricated at TSMC**. A production halt would delay rollouts of next-gen servers, force a return to older chips, and trigger a **race to hoard inventory**, ultimately degrading performance across the internet economy.

Across all these sectors, the effect is not just economic—it is **strategic exposure**. The realization that the digital world has a single-point-of-failure would provoke **corporate and state-level panic**.

9.2 Medium-Term Restructuring of Global Semiconductor Geography

Within months of TSMC’s incapacitation, the shock would catalyze an **accelerated restructuring of global semiconductor geography**. The process already underway—driven by geopolitical fears, industrial policy, and national security concerns—would now become a **crash program** across multiple nations:

- **United States:** The CHIPS Act would be turbocharged. Intel, GlobalFoundries, and TSMC’s Arizona facility would be flooded with emergency funding. Regulatory barriers would be swept aside to accelerate fab construction and workforce development. **Licensing regimes and export controls** would tighten around IP and manufacturing knowledge to prevent leakage to adversaries.
- **Europe:** The EU’s own Chips Act would shift from bureaucratic planning to industrial mobilization. France, Germany, and the Netherlands would race to **expand domestic capacity**, with heavy subsidies for ASML, STM, and Infineon. The emphasis would shift from efficiency to **sovereignty**.
- **Japan and South Korea:** As existing fab nations, they would seek to **absorb overflow investment**, consolidate their position as trusted suppliers, and hedge against dependence on U.S. or Chinese capacity. Samsung and Rapidus would likely benefit from redirected demand.
- **India and Southeast Asia:** Countries like India, Vietnam, and Malaysia would be **fast-tracked into the supply chain**, often as locations for assembly, testing, and packaging (OSAT), rather than leading-edge logic nodes. But this realignment would still mark a historic **reordering of trust networks**.

The end result would be the **fragmentation of the global semiconductor ecosystem**—away from Taiwan-centric efficiency and toward **redundant, politically aligned manufacturing blocs**.

9.3 Long-Term Acceleration of Techno-Economic Bloc Formation

Beyond the practical reshuffling of fabs and suppliers, the destruction of TSMC would crystallize a **new global architecture of techno-economic blocs**. This is not just supply chain diversification—it is **civilizational divergence**.

In this emerging order:

- The **U.S.-led bloc** would double down on vertical integration, treating chips as a **strategic resource akin to oil in the 20th century**. Nations wishing to access this network—via

chips, software, cloud infrastructure, or research partnerships—would need to **align politically and ideologically**.

- The **China-led bloc** would shift from hybrid dependence to **full-stack autarky**, investing in domestic lithography, EDA tools, legacy node independence, and alternative computing paradigms (e.g. neuromorphic or analog AI). Losing access to TSMC would not delay this strategy—it would justify and accelerate it.
- **Neutral or hedging states** (India, Brazil, Gulf States) would be forced to **choose sides** or risk technological isolation. Chip diplomacy would replace trade negotiations. Access to 3nm nodes would become a **currency of geopolitical favor**.

Culturally, the long-term effect is the **normalization of techno-nationalism**. Open markets in semiconductors would be replaced by **permanent techno-fortresses**, complete with export controls, licensing regimes, talent restrictions, and AI arms control analogs.

In this new era, **the loss of TSMC is not just a supply shock**—it is the **starting gun** for a geopolitical realignment measured not in tariffs, but in transistors.

10. The End of the “Silicon Shield” Era

For the past two decades, Taiwan’s geopolitical position has been stabilized—at least in part—by the notion of a **“silicon shield.”** This term refers to the idea that Taiwan’s dominance in advanced semiconductor manufacturing, especially through TSMC, would serve as a deterrent to invasion. The logic held that **no one would risk destabilizing the global economy** or destroying the very infrastructure they needed to power their own technological ambitions.

But that era is now ending. The “silicon shield” was never a literal defense system; it was a strategic narrative—a belief in **mutual dependence as a source of restraint**. As this section shows, the destruction of TSMC’s leading-edge fabs, whether during or after an invasion, marks the **collapse of that logic**. What replaces it is not interdependence, but a world of hardened techno-blocs, where denial—not shared value—is the organizing principle of deterrence.

10.1 Why Mutual Dependence No Longer Guarantees Restraint

The premise behind the “silicon shield” was elegant: Taiwan produces the world’s most advanced chips, which both the West and China depend on. Therefore, attacking Taiwan would be **irrational**, as it would jeopardize access to a critical global resource.

But this premise no longer holds.

First, the **global consensus on rationality has fractured**. Strategic decisions are increasingly driven by political ideology, national security imperatives, and domestic legitimacy—not shared economic logic. China's calculus, in particular, is informed not just by supply chains but by historical grievances, reunification goals, and Communist Party legitimacy. It is entirely plausible that China would **choose to destroy access to chips if doing so furthered its long-term strategic goals**, especially if it believes the West is preparing to isolate it anyway.

Second, the West no longer assumes **mutual gain will prevent conflict**. The COVID-19 pandemic, the war in Ukraine, and escalating U.S.-China decoupling have shifted the mindset of global actors. Dependence is now viewed as **vulnerability**, not deterrence. The existence of TSMC in Taiwan is no longer seen as a stabilizing asset—it is seen as a **risk exposure** in need of mitigation.

In this environment, **mutual dependence breeds instability**, not restraint. The shield has become a liability.

10.2 Semiconductor Scarcity as a Feature, Not a Bug, of Future Geopolitics

The loss of TSMC's advanced fabs will create an unprecedented bottleneck in high-end chip supply. But rather than treat that scarcity as a crisis to be solved, emerging techno-political regimes may come to see it as **a tool of leverage and control**.

Scarcity allows governments to:

- **Gate access to strategic capabilities** such as AI compute, defense tech, and high-performance cloud systems
- **Extract political concessions** from allied states in exchange for priority access
- **Disrupt rivals' technological timelines** by denying them access to key components

This is already evident in the rise of **chip export controls** and restrictions on AI accelerator hardware. In a post-TSMC world, we can expect this logic to **intensify**. Rather than build toward open, global capacity, nations will **embrace fragmentation**, hoarding advanced node capabilities as national assets akin to rare earth metals or nuclear enrichment technology.

This means that **semiconductor scarcity is not a temporary problem to fix—it is becoming a structural feature of 21st-century geopolitics**, reshaping alliances and redefining power.

10.3 The Transition from Deterrence by Value to Deterrence by Denial

The “silicon shield” operated under a model of **deterrence by value**: the idea that Taiwan’s economic and technological value to the world would dissuade China from using force, because destroying that value would hurt everyone—including China.

That logic is being replaced by **deterrence by denial**: the idea that Taiwan, with or without allied support, must prevent China from **gaining anything of value** through invasion. This shift in strategic posture is already underway in defense planning circles. The new emphasis is not on preserving fabs but on ensuring that they **cannot be captured intact**—by any means necessary.

This includes:

- Remote kill switches and digital denial protocols embedded in key tools
- Pre-positioned plans for intentional disablement of critical process chains
- International coordination to **ensure embargoes render captured fabs useless**
- Strategic messaging to **disincentivize attempts at salvage-based conquest**

In this new framework, **loss is accepted**, but **strategic denial is maximized**. Taiwan may fall, but the world’s most valuable fabrication capacity will not fall with it. This transition—from deterrence by mutual interest to deterrence by foreclosed reward—marks the **true end of the silicon shield**.

And with it, the beginning of a harsher, colder era of semiconductor geopolitics.

11. Conclusion: Accepting the Industrial Reality of Modern War

The fantasy that TSMC's advanced semiconductor fabs can survive a Chinese invasion—physically, functionally, or strategically—has persisted for too long. Whether through process fragility, systemic disintegration, kinetic damage, or strategic denial, **the destruction of Taiwan’s most critical infrastructure is the most likely outcome of war**, not the worst-case scenario. This is not a failure of policy imagination. It is the inevitable result of material constraints, human systems, and adversarial incentives.

The time has come to accept that **TSMC’s destruction is not the thing to be avoided at all costs**, but the *reality around which we must plan*. This conclusion is neither defeatist nor fatalistic. It is the basis for sober, future-proofed strategy—one that views deterrence, resilience, and recovery not through optimism or techno-utopianism, but through **realism grounded in the physics of industrial warfare**.

11.1 Why TSMC's Destruction Is Not a Policy Failure but a Structural Outcome

No matter how carefully crafted, no deterrence strategy can alter the fact that semiconductor fabrication at 3nm and below depends on **extraordinarily delicate, continuous processes**.

These processes are not robust to geopolitical disruption. They are not restartable on command. And they are not capturable by force.

Therefore, the destruction of TSMC—if war comes—is not a failure of imagination, diplomacy, or defense. It is a **structural inevitability** baked into the convergence of modern warfare and ultra-precision industry.

This distinction matters. It shifts the narrative away from blame and toward architecture. Instead of asking who failed to protect TSMC, we must ask **how the world allowed itself to concentrate so much global capacity into one strategically exposed region**. The destruction of Taiwan's fabs is not a singular catastrophe. It is a **revealing consequence of decades of path-dependent globalization**—one that can no longer be reversed but must now be absorbed.

11.2 Planning for Loss Rather Than Preservation

If destruction is likely, then **strategy must be re-centered around denial, redundancy, and reconstitution**. This means that Taiwan, its allies, and the private sector must shift from fragile assumptions of fab survivability to **robust plans for fab elimination, compensation, and deterrence**.

This involves:

- **Pre-coordinated denial systems:** remote disablement, critical tool neutralization, and local sabotage plans that render fabs unusable within hours of invasion onset
- **Distributed fabrication capacity:** not simply diversifying to new countries, but ensuring critical nodes exist **within each techno-strategic bloc**
- **Pre-funded recovery pathways:** modular fab designs, portable process tuning frameworks, and stockpiles of key equipment to **rebuild capacity quickly after war**
- **Strategic communication that reinforces resolve:** making it clear to adversaries that **no gain will result from invasion**, even if fabs remain standing

This is not planning for failure. It is planning for **resilience under conditions where success is structurally impossible**.

11.3 What Realism Demands from Governments, Markets, and Technologists

Finally, realism imposes demands—on governments, on markets, and on the technologists whose work shapes tomorrow’s infrastructure.

- **Governments** must **speak with clarity**, funding not just domestic fabs, but entire sovereign stacks: lithography, EDA, packaging, talent. They must align export control regimes, crisis playbooks, and industrial policy with the assumption that **Taiwan may no longer be available as a linchpin**.
- **Markets** must abandon their love affair with just-in-time efficiency and lowest-cost consolidation. Supply chains must be measured not by quarterly margins but by **wartime survivability**. The question is no longer “what is cheapest,” but “what can continue if bombs fall.”
- **Technologists** must design with **systemic fragility in mind**. That means investing in heterogeneous compute architectures, analog fallbacks, and cross-node compatibility. It means reimagining the future not as a linear continuation of Moore’s Law, but as a complex terrain shaped by **war, scarcity, and strategic adaptation**.

The illusion of invulnerability has passed. TSMC’s destruction—if and when it comes—should not surprise us. What will define this generation is whether it was prepared not just **to mourn it**, but **to outlive it**.

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If Taiwan Falls, the Fabs Burn

The Inevitable Destruction of TSMC

